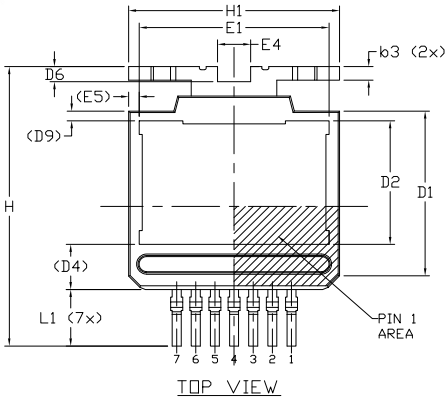


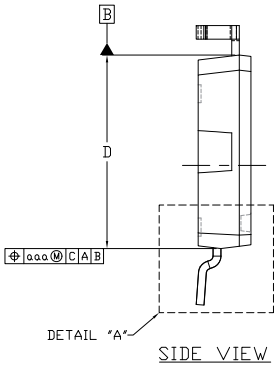
BPAK7 14.00x12.85x3.50, 1.27P

CASE 763AA
ISSUE A

DATE 16 OCT 2024



TOP VIEW



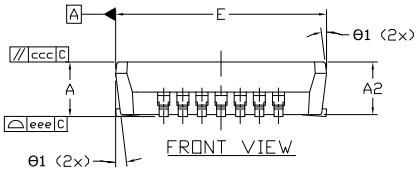
SIDE VIEW

NOTES:

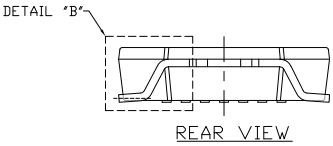
1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE.
4. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
5. DIMENSIONS A1 IS THE LEAD STAND-OFF FROM THE BOTTOM SURFACE OF THE PACKAGE BODY.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	3.53	3.63	3.73
A1	0.05	0.15	0.25
A2	3.40	3.50	3.60
b	0.50	0.60	0.70
b2	0.60	0.80	1.00
b3	0.80	0.90	1.00
c	0.45	0.55	0.65
D	12.75	12.85	12.95
D1	10.84	10.94	11.04
D2	7.85	8.10	8.35
D3	6.32 REF.		
D4	3.00 REF.		
D5	1.85	1.95	2.05
D6	0.90	1.00	1.10
D7	0.85	0.91	1.05
D8	0.90 REF.		
D9	0.82 REF.		
E	13.90	14.00	14.10
E1	12.50	12.60	12.70
E2	5.58	5.68	5.78

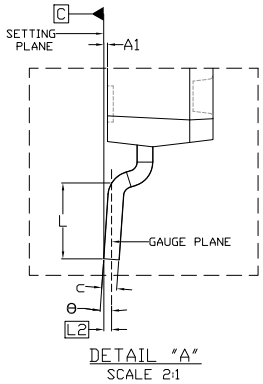
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
E3	2.79 REF.		
E4	2.10	2.20	2.30
E5	0.70 REF.		
e	1.27 BSC		
e1	7.62 BSC		
H	18.05	18.55	19.05
H1	13.80	14.00	14.20
L	2.32	2.47	2.62
L1	3.65	3.75	3.85
L2	0.26 BSC		
L3	1.79	1.89	1.99
P	2.40	2.50	2.60
Θ	0°	---	8°
Θ1	0°	---	7°
aaa	0.20		
bbb	0.25		
ccc	0.20		
ddd	0.20		
eee	0.20		



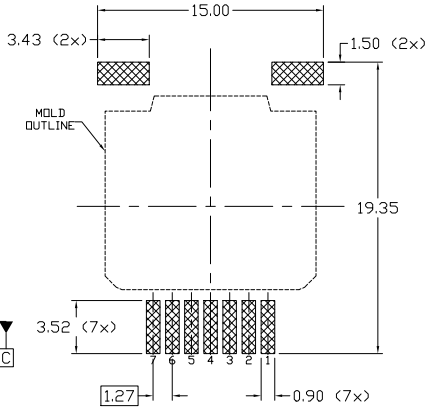
FRONT VIEW



REAR VIEW

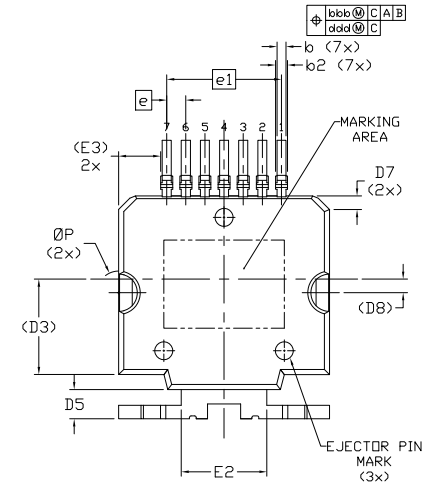


DETAIL "A"
SCALE 2:1

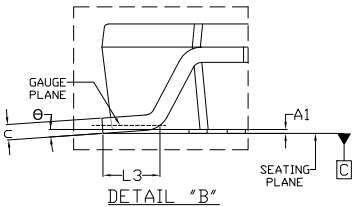


RECOMMENDATION MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

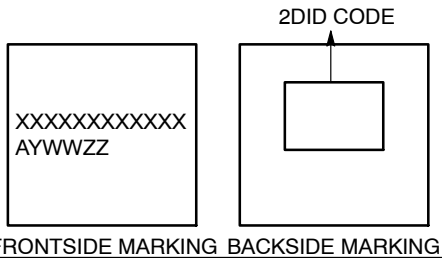


BOTTOM VIEW



DETAIL "B"
SCALE 2:1

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
ZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

FRONTSIDE MARKING BACKSIDE MARKING

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